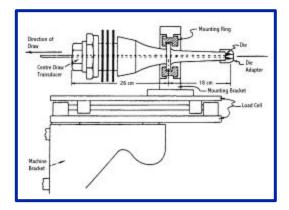
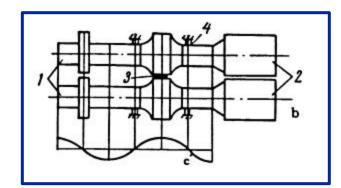
Ultrasonic Drawing of Composite Superconducting Wire



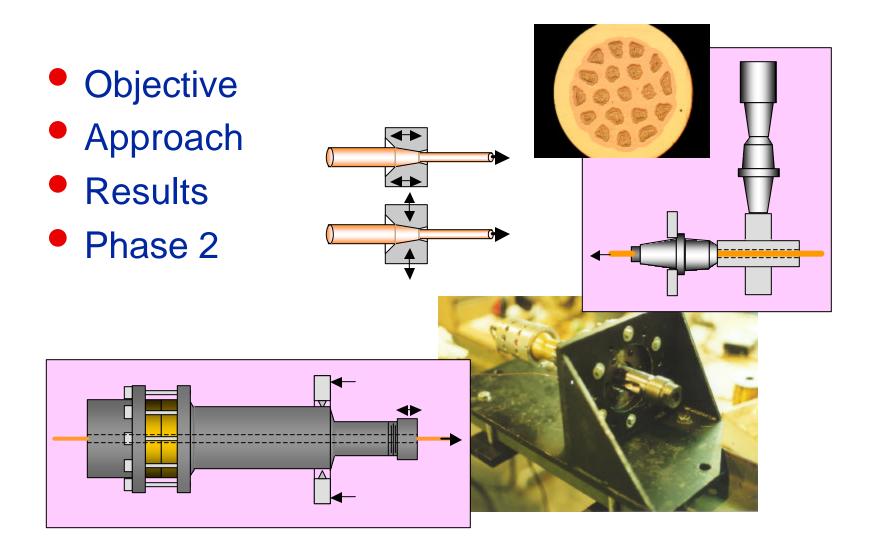
Karl Graff, EWI/Global Mike Tomsic, Global Edward Collings, OSU







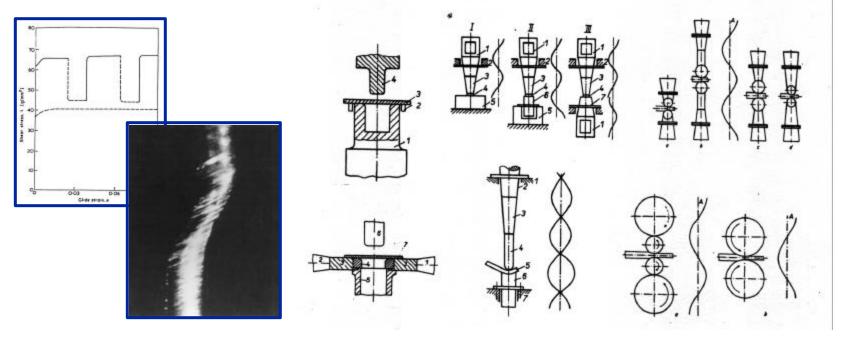
Outline





USWD - Background

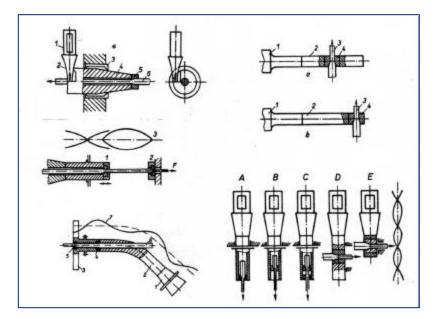
- "Acoustic softening" report led to much work in metal forming
- Deformation mechanism still unclear (acoustic softening or superposition)

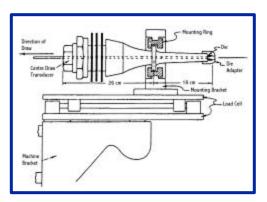




USWD - Background

- Extensive work in WD/TD continues
- Advantages sought (reduce force, area reduction, finish, die life, speed)
- Specialty applications

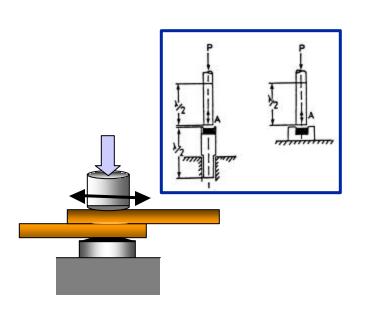






Current Application

- Superconducting wire
- Key issue breakage
- Bonding/consolidation
- Global/OSU background

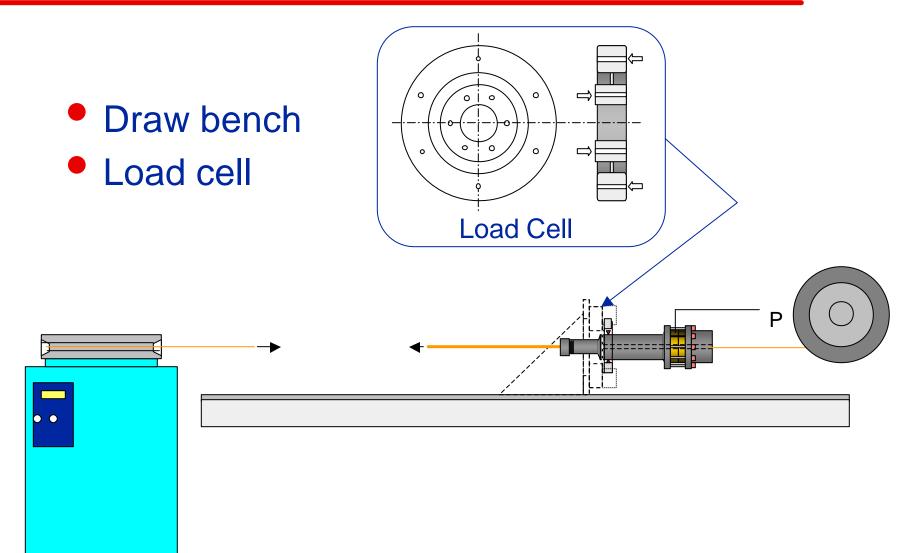








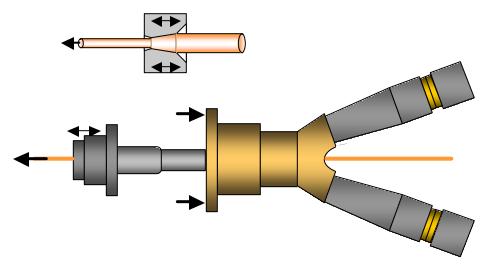
Wire Drawing System

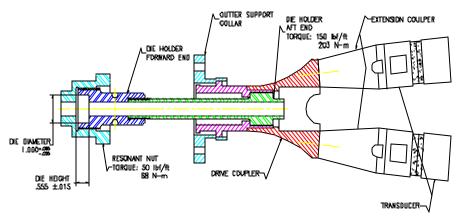


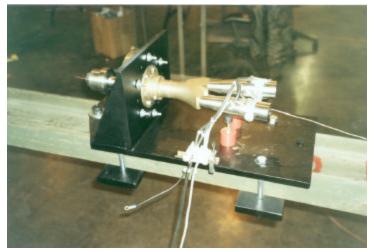


Y-Coupler System

- LM system
- 28 kHz, rigid mount
- Results, Plan B



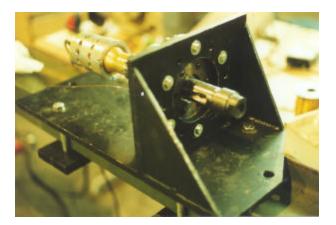


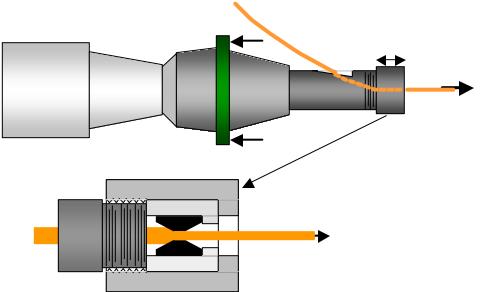




Side Draw System

- Standard Xducer, booster
- Special sonotrode
- Results

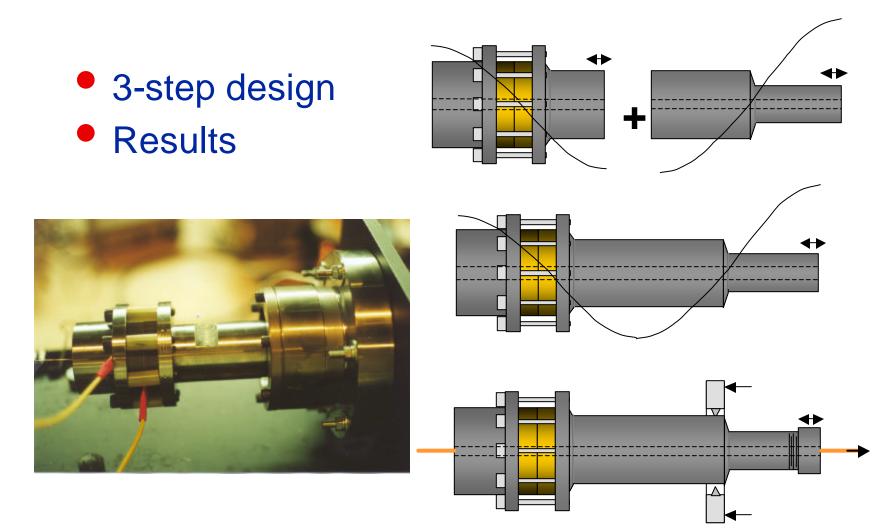








Center Draw System



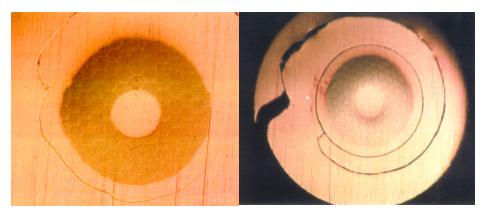


Results – Phase 1

- Plan B1, B2 systems developed
- Draw force reductions
- Evidence of bonding



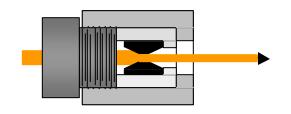
System	% Force Reduction
Side Draw	29
Center Draw	26

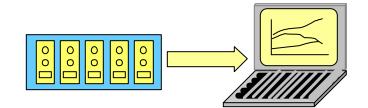


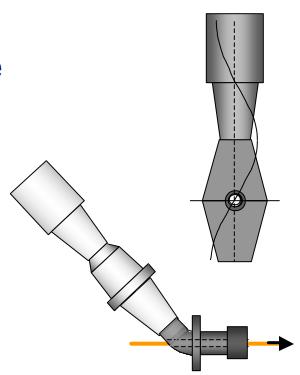


Phase 2 – Objective/Approach

- Can US yield long draws, other benefits?
- Optimize LM system
- Develop radial mode
- Die design
- Instrumentation

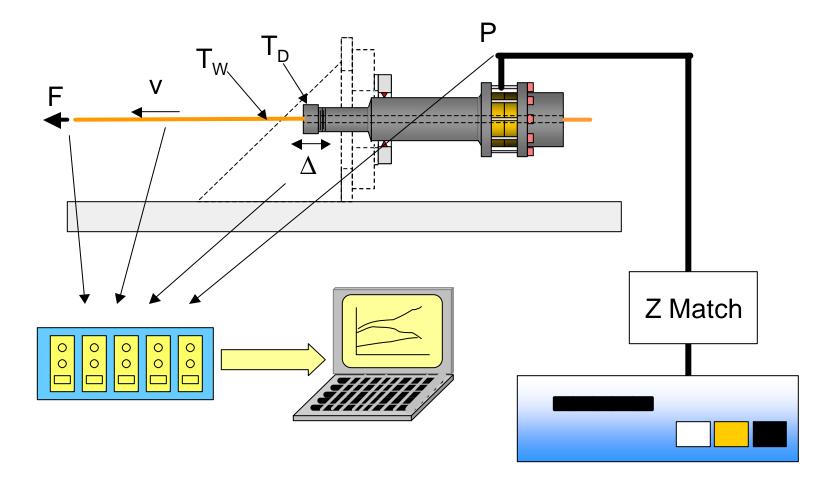








Instrumentation





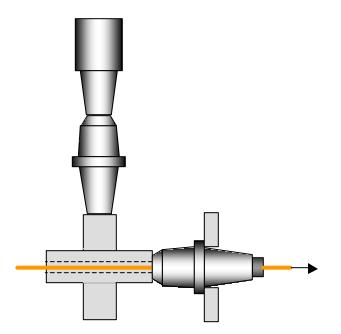
Longitudinal Mode Options

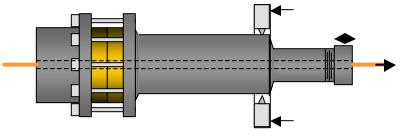
1) Side draw 1 2) Center draw 2) 3) Y-coupler 4) Cross die 5) Curved line 3) 4) 5)



LM Systems

- Cross die design load cell
- New CD system match to standard PS
- Die design

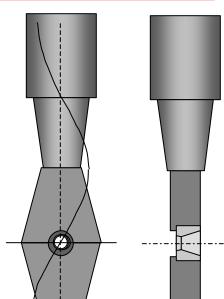


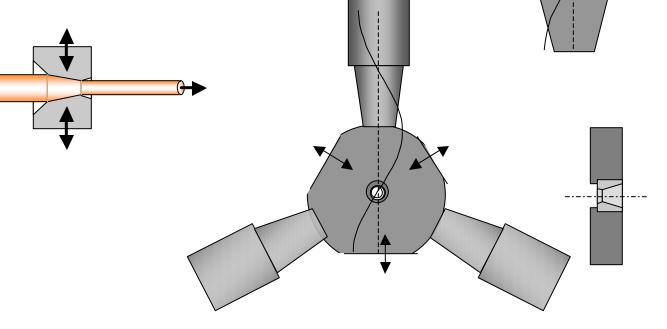




Radial Mode Systems

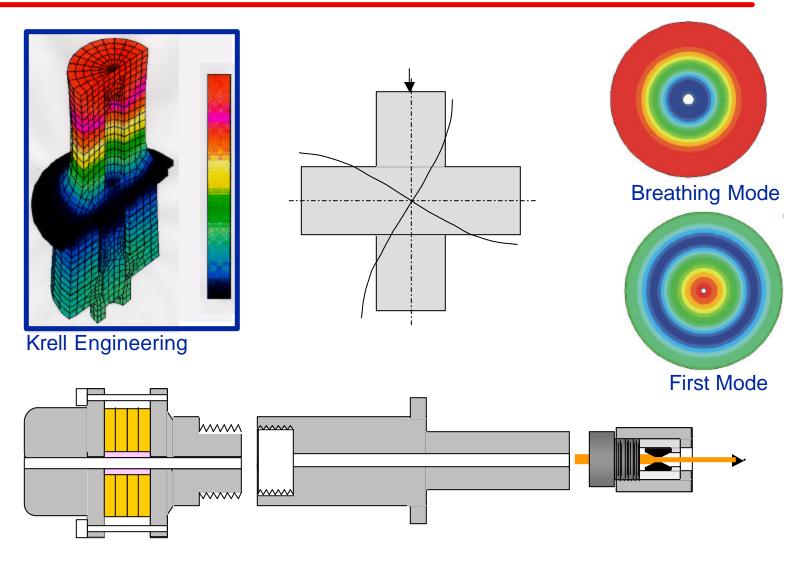
- Enhance compaction
- Small diameter less
 US action
- Complex modes







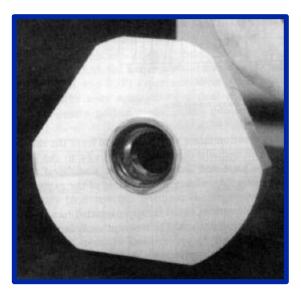
FEA of US Components

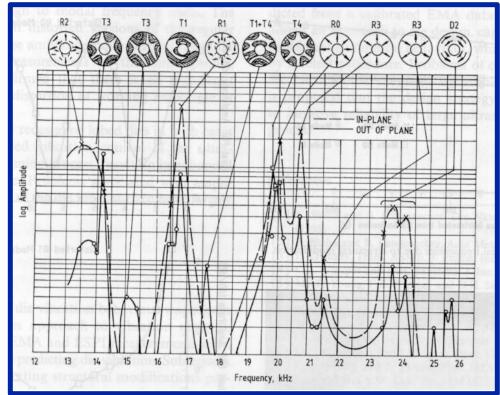




Prior Work

Lucas ('96)







Summary

- "B1, B2" WD systems developed
- Draw forces reduced
- Bonding achieved
- Phase 2 in-depth development of LM and RM systems

